# Single Non-Inverting Buffer with Schmitt Trigger

The NL17SZ17 is a single Non–inverting Schmitt Trigger Buffer in two tiny footprint packages. The device performs much as LCX multi–gate products in speed and drive.

## Features

- Tiny SOT-353 and SOT-553 Packages
- Source/Sink 24 mA at 3.0 Volts
- Overvoltage Tolerant Inputs and Outputs
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- Pb–Free Packages are Available



Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



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http://onsemi.com



- LX = Device Marking
- D = One Digit Date Code

#### PIN ASSIGNMENT

Pin	Function
1	NC
2	А
3	GND
4	Y
5	V <sub>CC</sub>

#### FUNCTION TABLE

A Input	Y Output
L	L
Н	Н

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

## **MAXIMUM RATINGS**

Symbol	P	arameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \leq V_{I} \leq +7.0$	V
Vo	DC Output Voltage	Output in High or LOW State (Note 1)	$-0.5 \le V_O \le 7.0$	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>I</sub> < GND	-50	mA
Ι <sub>ΟΚ</sub>	DC Output Diode Current	V <sub>O</sub> < GND	-50	mA
Ι <sub>Ο</sub>	DC Output Sink Current		±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case f	or 10 Seconds	260	°C
TJ	Junction Temperature under Bias		+ 150	°C
$\theta_{JA}$	Thermal Resistance	SOT-353 (Note 2) SOT-553	350 496	°C/W
PD	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	Ĩ
I <sub>Latchup</sub>	Latchup Performance	Above $V_{CC}$ and Below GND at 85°C (Note 6)	±500	mA
ESD	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model	Class IC Class A N/A	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I<sub>O</sub> absolute maximum rating must be observed.

Bassoured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

4. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

5. Tested to JESD22-C101-A.

6. Tested to EIA/JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Paramete	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage, (Note 7)		0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	5.5	V
T <sub>A</sub>	Operating Free-Air Temperature		- 40	+ 85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 V \pm 0.2 V V_{CC} = 3.0 V \pm 0.3 V V_{CC} = 5.0 V \pm 0.5 V$	0 0 0	No Limit No Limit No Limit	ns/V

7. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

## DC ELECTRICAL CHARACTERISTICS

			V <sub>cc</sub>	T <sub>A</sub> =	= 25°C		$-40^{\circ}C \leq T_{A}$	≤ <b>85°C</b>	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>T</sub> +	Positive Input Threshold Voltage		1.65 2.3 2.7 3.0 4.5 5.5	0.6 1.0 1.2 1.3 1.9 2.2	1.0 1.5 1.7 1.9 2.7 3.3	1.4 1.8 2.0 2.2 3.1 3.6	0.6 1.0 1.2 1.3 1.9 2.2	1.4 1.8 2.0 2.2 3.1 3.6	V
V <sub>T</sub> -	Negative Input Threshold Voltage		1.65 2.3 2.7 3.0 4.5 5.5	0.2 0.4 0.5 0.6 1.0 1.2	0.5 0.75 0.87 1.0 1.5 1.9	0.8 1.15 1.4 1.5 2.0 2.3	0.2 0.4 0.5 0.6 1.0 1.2	0.8 1.15 1.4 1.5 2.0 2.3	V
V <sub>H</sub>	Input Hysteresis Voltage		1.65 2.3 2.7 3.0 4.5 5.5	0.1 0.25 0.3 0.4 0.6 0.7	0.48 0.75 0.83 0.93 1.2 1.4	0.9 1.1 1.15 1.2 1.5 1.7	0.1 0.25 0.3 0.4 0.6 0.7	0.9 1.1 1.15 1.2 1.5 1.7	V
V <sub>OH</sub>	High–Level Output Voltage $V_{IN} = V_{IH}$ or $V_{IL}$	$\begin{split} I_{OH} &= -100 \; \mu A \\ I_{OH} &= -3 \; m A \\ I_{OH} &= -8 \; m A \\ I_{OH} &= -12 \; m A \\ I_{OH} &= -16 \; m A \\ I_{OH} &= -24 \; m A \\ I_{OH} &= -32 \; m A \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	$\begin{array}{c} V_{CC} \ -0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{array}$	V <sub>CC</sub> 1.52 2.1 2.4 2.7 2.5 4.0		$\begin{array}{c} V_{CC} \ -0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{array}$		V
V <sub>OL</sub>	Low–Level Output Voltage $V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 100 \ \mu A$ $I_{OL} = 4 \ mA$ $I_{OL} = 8 \ mA$ $I_{OL} = 12 \ mA$ $I_{OL} = 16 \ mA$ $I_{OL} = 24 \ mA$ $I_{OL} = 32 \ mA$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	$V_{IN} = 5.5 \text{ V or GND}$	0 to 5.5			±0.1		±1.0	μΑ
I <sub>OFF</sub>	Power Off–Output Leakage Current	V <sub>OUT</sub> = 5.5 V	0			1.0		10	μA
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		10	μΑ

#### AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$ )

			v <sub>cc</sub>	T <sub>A</sub> = 25°C		-40°C ≤ -			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Unit
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Input A to Y (Figures 3 and 4)	$R_L = 1 M\Omega$ , $C_L = 15 pF$	$\begin{array}{c} 1.65 \\ 1.8 \\ 2.5 \pm 0.2 \\ 3.3 \pm 0.3 \\ 5.0 \pm 0.5 \end{array}$	2.0 2.0 1.0 1.0 0.5	9.1 7.6 5.0 3.7 3.1	15 12.5 9.0 6.3 5.2	2.0 2.0 1.0 1.0 0.5	15.6 13 9.5 6.5 5.5	ns
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$	$\begin{array}{c} 3.3  \pm  0.3 \\ 5.0  \pm  0.5 \end{array}$	1.5 0.8	4.4 3.7	7.2 5.9	1.5 0.8	7.5 6.2	

## **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	>2.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 8)	10 MHz, $V_{CC}$ = 3.3 V, $V_I$ = 0 V or $V_{CC}$ 10 MHz, $V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	9 11	pF

8.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

# NL17SZ17











	Device Nomenclature								
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape/Reel Size <sup>†</sup>
NL17SZ17DFT2	NL	1	7	SZ	17	DF	T2	SOT-353/SC70-5/ SC-88A	178 mm, 3000 Units
NL17SZ17DFT2G	NL	1	7	SZ	17	DF	T2	SOT-353/SC70-5/ SC-88A (Pb-Free)	178 mm, 3000 Units
NL17SZ17XV5T2	NL	1	7	SZ	17	XV5	T2	SOT-553* (Pb-Free)	178 mm, 4000 Units

#### **DEVICE ORDERING INFORMATION**

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

## NL17SZ17

## PACKAGE DIMENSIONS

SOT-353 **DF SUFFIX** 5-LEAD PACKAGE CASE 419A-02 ISSUE G



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
Κ	0.004	0.012	0.10	0.30
Ν	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### NL17SZ17

#### PACKAGE DIMENSIONS

SOT-553 XV5 SUFFIX 5-LEAD PACKAGE CASE 463B-01 ISSUE A



NOTES: 1. DIMENSI

ST

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.50	1.70	0.059	0.067	
В	1.10	1.30	0.043	0.051	
С	0.50	0.60	0.020	0.024	
D	0.17	0.27	0.007	0.011	
G	0.50	BSC	0.020 BSC		
J	0.08	0.18	0.003	0.007	
Κ	0.10	0.30	0.004	0.012	
S	1.50	1.70	0.059	0.067	

	STYLE 2:	
BASE 1	PIN 1.	CATHODE
EMITTER 1/2	2.	ANODE
BASE 2	3.	CATHODE
COLLECTOR 2	4.	CATHODE
COLLECTOR 1	5.	CATHODE
	BASE 1 EMITTER 1/2 BASE 2 COLLECTOR 2 COLLECTOR 1	BASE 1     PIN 1.       EMITTER 1/2     2.       BASE 2     3.       COLLECTOR 2     4.

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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